

## Flyback Transformers For STMicroelectronics POTS interface



- · Developed for the ST Micro STL3075 and STL3085 Integrated POTS interfaces for home access gateway and WLL.
- Provides negative voltage (-46 V typical) to operate the

## Core material Ferrite

Interwinding isolation 1500 Vdc

Terminations RoHS tin-silver over tin over nickel over phos bronze. Other terminations available at additional cost.

Weight 1.9 - 2.1 g

Ambient temperature -40°C to +85°C

Storage temperature Component: -40°C to +85°C.

Packaging: -55°C to +80°C

Resistance to soldering heat Max three 40 second reflows at +260°C, parts cooled to room temperature between cycles

Moisture Sensitivity Level (MSL) 1 (unlimited floor life at <30°C/ 85% relative humidity)

Failures in Time (FIT) / Mean Time Between Failures (MTBF) 38 per billion hours / 26,315,789 hours, calculated per Telcordia SR-332

Packaging 350 per 13" reel Plastic tape: 32 mm wide, 0.42 mm thick, 20 mm pocket spacing, 9.16 mm pocket depth

PCB washing Only pure water or alcohol recommended

Part	Inductance at 0 A <sup>2</sup>	Inductance at Ipk <sup>3</sup>	DCR ma	x (Ohms)	Leakage inductance <sup>4</sup>	Turns ratio	<b>Ipk</b> <sup>3</sup>	Input
number <sup>1</sup>	±8% (µH)	min (μH)	pri	sec	max (µH)	pri : sec	(A)	voltage (V)
FA2469-AL_	19	14.86	0.036	16.5	0.414	1:16	1.5	4.5 - 8.5
FA2470-AL_	19	14.86	0.036	7.92	0.400	1:8	1.5	8.5 - 12.0

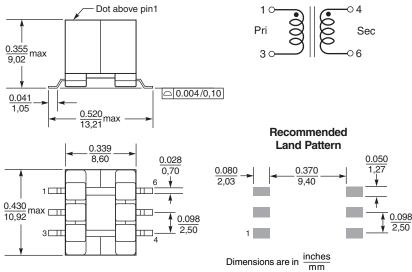
1. When ordering, please specify packaging code:

## FA2470-AL D

Packaging: D = 13" machine-ready reel. EIA-481 embossed plastic tape (350 parts per full reel).

- B = Less than full reel. In tape, but not machine ready. To have a leader and trailer added (\$25 charge), use code letter D instead.
- 2. Inductance is for the primary, measured at 10 kHz, 0.1 Vrms, 0 Adc.
- 3. Ipk is peak primary current drawn at minimum input voltage.
- 4. Leakage inductance measured between pins 1 and 3 with pins 4 and 6 shorted.
- 5. Operating temperature range -40°C to +85°C.
- 6. Electrical specifications at 25°C.

Refer to Doc 362 "Soldering Surface Mount Components" before soldering.



Specifications subject to change without notice. Please check our website for latest information.

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